

RELIABILITY REPORT
FOR
MAX4545CEE+
(MAX4545 – MAX4547)
PLASTIC ENCAPSULATED DEVICES

December 10, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Conclusion

The MAX4545CEE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4545/MAX4546/MAX4547 are low-voltage T-switches designed for switching RF and video signals from DC to 300MHz in 50 and 75 systems. The MAX4545 contains four normally open single-pole/single-throw (SPST) switches. The MAX4546 contains two dual SPST switches (one normally open, one normally closed.) The MAX4547 contains two single-pole/double-throw (SPDT) switches. Each switch is constructed in a "T" configuration, ensuring excellent high-frequency off isolation and crosstalk of -80dB at 10MHz. They can handle rail-to-rail analog signals in either direction. On-resistance (20 max) is matched between switches to 1 max and is flat (0.5 max) over the specified signal range, using $\pm 5V$ supplies. The off leakage current is less than 5nA at +25°C and 50nA at +85°C. These CMOS switches can operate with dual power supplies ranging from $\pm 2.7V$ to $\pm 6V$ or a single supply between +2.7V and +12V. All digital inputs have 0.8V/2.4V logic thresholds, ensuring both TTL- and CMOS-logic compatibility when using $\pm 5V$ or a single +5V supply.

II. Manufacturing Information

A. Description/Function:	Quad/Dual, Low-Voltage, Bidirectional RF Video Switches
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Carsem Malaysia, ATP Philippines, UTL Thailand
F. Date of Initial Production:	June 25, 1997

III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0020
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

IV. Die Information

A. Dimensions:	101 X 85 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.4 \times 10^{-9}$$
$$\lambda = 13.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S3 Process results in a FIT Rate of 3.6 @ 25C and 66.0 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AH01-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4545CEE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data